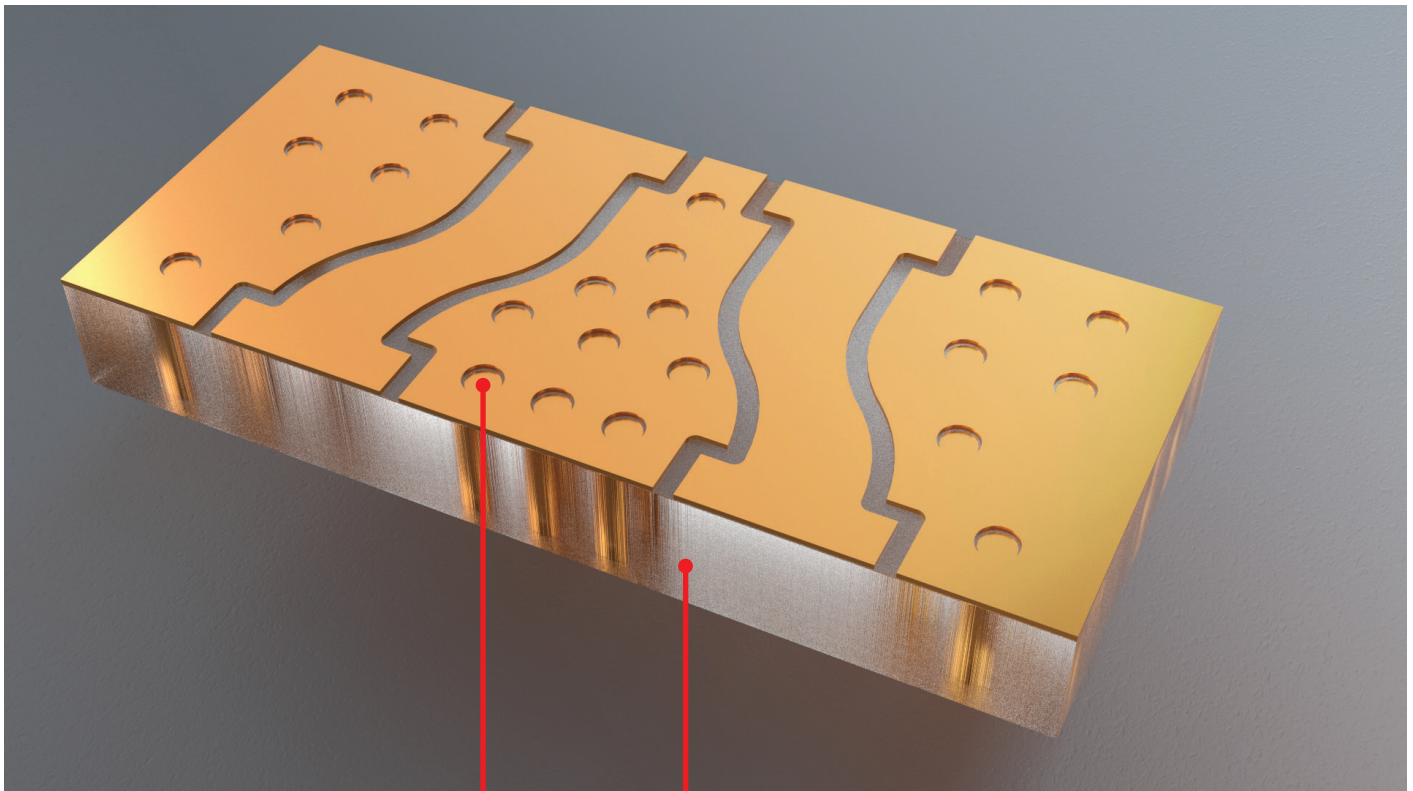


IMPEDANCE MATCHED, LOW LOSS

RF BRIDGES

Improve Performance and Reduce Footprint

Precisely match impedance values with reduced footprints and heights.



Thru-Glass VIAS (TGV)

Precision TGVs ensure fully grounded devices between top and bottom metal

Glass Substrate and Frame

Easy handling of device with glass support structure; flip-chip, SMT, or wire-bonding design and surface finish options

Precision Impedance Matching

Precision thickness from 90 microns and up enable precision impedance matching

Grounded Co-Planner Design

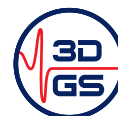
Low-loss glass substrate and TGVs enable precise impedance matching



1-505-916-5590



3DGSinc.com



Enabling the GHz Generation

IMPEDANCE MATCHED, LOW LOSS

RF BRIDGES

Custom RF Bridges

RF bridges are incorporated to improve circuit-to-circuit electrical connections by utilizing an impedance-matched RF bridge chip with uniform wire bond lengths. These RF bridges are custom designed to meet customer-specific bridging requirements for chip integration and height.

Grounded Co-Planar Waveguide Design

3DGS RF bridges utilize low-loss glass substrates with TGVs which allow RF waveguides to have grounding along both sides and below the transmission line for highest performance.

Top wire pads are compatible with wire bonding.

Highly Scalable

Lithographic reproduction processes facilitate mass production of devices with superior batch-to-batch consistency.

Specifications

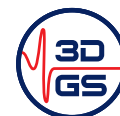
PARAMETERS	TYPICAL PERFORMANCE
Impedance values	25 Ω to 100 Ω
Thickness	90 μm to 800 μm
Attenuation (dB)	As low as 0.3 dB/cm at 30 GHz
Size	As small as 0.5 mm x 0.5 mm
Operating Temperature	SMT -55°C to +155°C
Compliance	RoHS



1-505-916-5590



3DGSinc.com



Enabling the GHz Generation